

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **06/14/2022**

Details for "TPS7A4101DGNT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7A4101DGNT	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DGN 8	3x3x1	31.4

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.055074	100	1000000	0.175216	1752
Sub-Total			0.055074	100	1000000	0.175216	1752
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.317293	75.000059	750001	1.009456	10095
Thermoplastics	Epoxy	85954-11-6	0.105764	24.999941	249999	0.336484	3365
Sub-Total			0.423057	100	1000000	1.34594	13459
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	14.535	96.9	969000	46.242555	462426
Nickel and Its Alloys	Nickel	7440-02-0	0.3765	2.51	25100	1.197821	11978
Other Inorganic Materials	Silicon	7440-21-3	0.066	0.44	4400	0.209977	2100
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.0225	0.15	1500	0.071583	716
Sub-Total			15	100	1000000	47.721935	477219
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.294872	95.12	951200	0.938124	9381
Precious Metals	Gold	7440-57-5	0.002418	0.78	7800	0.007693	77
Precious Metals	Palladium	7440-05-3	0.01271	4.1	41000	0.040436	404
Sub-Total			0.31	100	1000000	0.986253	9863
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	11.630865	86.999996	870000	37.003159	370032
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	0.922448	6.9	69000	2.934734	29347
Other Plastics and Rubber	Carbon Black	1333-86-4	0.013369	0.100001	1000	0.042533	425
Thermoplastics	Epoxy	85954-11-6	0.802129	6.000003	60000	2.551943	25519
Sub-Total			13.368811	100	1000000	42.532368	425324
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.275145	100	1000000	7.238288	72383
Sub-Total			2.275145	100	1000000	7.238288	72383
Total			31.432087			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.